

What is claimed is:

1. A thermosetting resin sheet for sealing an electronic component, comprising one or more resin components and an inorganic filler, wherein~~optionally~~ one of the resin components is a thermoplastic resin, and ~~optionally~~ the thermosetting resin sheet has a content by percentage of the thermoplastic resin of a nonzero percentage which is not more than 30% or less by weight of all of the resin components,
 wherein a content by percentage of the inorganic filler is from 70% to 95% by weight of the thermosetting sheet,
 wherein after the thermosetting resin sheet is bonded onto a silicon nitride film formed on a silicon wafer and then set, the thermosetting resin sheet has a shear adhesive strength of 15 MPa or more at 25°C, and 2 MPa or more at 260°C,
 wherein after the thermosetting resin sheet is bonded onto a copper plate and then set, the thermosetting resin sheet has a shear adhesive strength of 10 MPa or more at 25°C, and 0.5 MPa or more at 260°C, and
 wherein after the thermosetting resin sheet is bonded onto a glass fabric based epoxy resin substrate and then set, the thermosetting resin sheet has a shear adhesive strength of 10 MPa or more at 25°C, and 1 MPa or more at 260°C, and
 wherein the thermosetting resin sheet further comprises a curing promoter.

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2. The thermosetting resin sheet according to claim 1,
which is produced by kneading extrusion.

3. A resin-sealed type semiconductor device, obtained by
5 use of the thermosetting resin sheet recited in claim 1.

4. A method for producing a resin-sealed type
semiconductor device, comprising the step of using the
thermosetting resin sheet recited in claim 1 to seal an
10 electronic component.

5. The thermosetting resin sheet according to claim 1,
wherein the one or more resin components comprise an epoxy
resin.

15 6. The thermosetting resin sheet according to claim 1,
wherein the one or more resin components comprise a phenol
resin.

20 7. The thermosetting resin sheet according to claim 1,
wherein the one or more resin components comprise an epoxy
resin and a phenol resin, wherein a total content by
percentage of the epoxy resin and the phenol resin is from
50% to 100% by weight of all of the resin components.

25 8. The thermosetting resin sheet according to claim 1,
wherein the one of the resin components is the
thermoplastic resin.

30 9. The thermosetting resin sheet according to claim 8,

wherein a content by percentage of the thermoplastic resin is not more than 15% by weight of all of the resin components.

5 10. The thermosetting resin sheet according to claim 8, wherein the thermoplastic resin comprises styrene/isobutylene/styrene block copolymer.

10 11. The thermosetting resin sheet according to claim 8, wherein a softening point of the thermoplastic resin is 120°C or higher.

15 12. The thermosetting resin sheet according to claim 8, wherein a softening point of the thermoplastic resin is 150°C or higher.

20 13. The thermosetting resin sheet according to claim 8, wherein a softening point of the thermoplastic resin is 190°C or lower.

25 14. The thermosetting resin sheet according to claim 8, wherein a softening point of the thermoplastic resin is 170°C or lower.

30 15. The thermosetting resin sheet according to claim 1, wherein the content by percentage of the inorganic filler is from 80% to 90% by weight of the thermosetting resin sheet.

30 16. The thermosetting resin sheet according to claim 1,

wherein the content by percentage of the inorganic filler is from 85% to 90% by weight of the thermosetting resin sheet.

5 17. The thermosetting resin sheet according to claim 1, wherein the curing promoter is present in an amount that is 0.1 to 5.0 parts by weight per 100 parts by weight of all of the resin components.

10 18. The thermosetting resin sheet according to claim 10, wherein a softening point of the styrene/isobutylene/styrene block copolymer is 120°C or higher.